

**IPC MARKET RESEARCH**

# PCB Technology Trends 2018



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# TABLE OF CONTENTS

Introduction .....	1
<b>Section 1: All Responses</b>	
Demographics	
Geographic Representation.....	3
Roles of Respondents .....	5
Applications	
Vertical End-Product Markets.....	6
Product Types: Mobile versus Installed.....	7
OEM Technology Requirements	
Emerging Technologies.....	10
Product Requirements (Frequency, Product Life Expectancy, Cycles per Day and Test Environment) .....	12
Board Properties and Requirements	
Board Thickness .....	14
Layer Counts .....	15
Density.....	19
Line Width and Spacing.....	21
Via Diameter .....	23
Aspect Ratios.....	24
Blind Vias.....	25
Buried Vias .....	26
Via Design .....	27
I/O Pitch .....	28
I/O Count .....	29
Thermal Properties .....	30
Materials and Finishes	
Substrate Materials.....	31
Metal Core .....	33
Loss Characteristics .....	33
Stretchable Circuits.....	34
Final Finishes.....	35
Special Technologies in PCB Fabrication	
Embedded Components.....	37
Chip Packages, Substrates and Modules.....	38
Printed Electronics.....	39
3D Printing .....	40
E-Textiles.....	41
Capital Investment Plans in the PCB Industry.....	42
Technical Challenges .....	43

## **Section 2: North America and Europe**

Demographics	
Geographic Representation.....	46
Roles of Respondents .....	48
Applications	
Vertical End-Product Markets.....	49
Product Types: Mobile vs. Installed.....	50
OEM Technology Requirements	
Emerging Technologies .....	52
Product Requirements (Frequency, Product Life Expectancy, Cycles per Day and Test Environment) .....	54
Board Properties and Requirements	
Board Thickness.....	56
Layer Counts .....	57
Density .....	61
Line Width and Spacing.....	63
Via Diameter.....	65
Aspect Ratios.....	66
Blind Vias .....	67
Buried Vias .....	68
Via Design .....	69
I/O Pitch .....	70
I/O Count .....	71
Thermal Properties .....	72
Materials and Finishes	
Substrate Materials.....	73
Metal Core .....	75
Loss Characteristics .....	75
Stretchable Circuits.....	76
Final Finishes.....	77
Special Technologies in PCB Fabrication	
Embedded Components .....	79
Chip Packages, Substrates and Modules.....	80
Printed Electronics.....	81
E-Textiles.....	81
Capital Investment Plans in the PCB Industry.....	82
Technical Challenges .....	83

## **Section 3: Asia and Africa**

Demographics	
Geographic Representation.....	86
Roles of Respondents .....	88
Applications	
Vertical End-Product Markets.....	89
Product Types: Mobile vs. Installed.....	90
OEM Technology Requirements	
Emerging Technologies .....	92
Product Requirements (Frequency, Product Life Expectancy, Cycles per Day	

and Test Environment) .....	94
<b>Board Properties and Requirements</b>	
Board Thickness .....	96
Layer Counts .....	97
Density.....	101
Line Width and Spacing.....	103
Via Diameter .....	105
Aspect Ratios.....	106
Blind Vias .....	107
Buried Vias .....	108
Via Design .....	109
I/O Pitch .....	110
I/O Count .....	111
Thermal Properties .....	112
<b>Materials and Finishes</b>	
Substrate Materials.....	113
Metal Core .....	115
Loss Characteristics .....	115
Stretchable Circuits.....	116
Final Finishes.....	117
<b>Special Technologies in PCB Fabrication</b>	
Embedded Components .....	119
Chip Packages, Substrates and Modules.....	120
Printed Electronics .....	121
3D Printing .....	122
E-Textiles .....	122
Capital Investment Plans in the PCB Industry.....	123
Technical Challenges .....	124

## **Section 4: Installed Products**

<b>Demographics</b>	
Geographic Representation.....	126
Roles of Respondents .....	128
<b>Applications</b>	
Vertical End-Product Markets.....	129
Product Types.....	130
<b>OEM Technology Requirements</b>	
Emerging Technologies .....	131
Product Requirements (Frequency, Product Life Expectancy, Cycles per Day and Test Environment) .....	133
<b>Board Properties and Requirements</b>	
Board Thickness .....	135
Layer Counts .....	136
Density.....	140
Line Width and Spacing.....	142
Via Diameter .....	144
Aspect Ratios.....	145
Blind Vias .....	146

Buried Vias .....	147
Via Design .....	148
I/O Pitch .....	149
I/O Count .....	150
Thermal Properties .....	151
<b>Materials and Finishes</b>	
Substrate Materials.....	152
Metal Core .....	154
Loss Characteristics .....	154
Stretchable Circuits.....	155
Final Finishes.....	156
<b>Special Technologies in PCB Fabrication</b>	
Embedded Components .....	158
Chip Packages, Substrates and Modules.....	159
Printed Electronics.....	160
3D Printing .....	160
E-Textiles.....	161
<b>Capital Investment Plans in the PCB Industry.....</b>	162
<b>Technical Challenges .....</b>	163
 <b>Section 5: Mobile Devices</b>	
<b>Demographics</b>	
Geographic Representation.....	165
Roles of Respondents .....	166
<b>Applications</b>	
Vertical End-Product Markets.....	167
Product Types.....	167
<b>OEM Technology Requirements</b>	
Emerging Technologies .....	168
Product Requirements (Frequency, Product Life Expectancy, Cycles per Day and Test Environment) .....	170
<b>Board Properties and Requirements</b>	
Board Thickness .....	172
Layer Counts .....	173
Density.....	175
Line Width and Spacing.....	175
Aspect Ratios.....	176
Blind and Buried Vias .....	177
I/O Pitch .....	178
I/O Count .....	178
Thermal Properties .....	179
<b>Materials and Finishes</b>	
Substrate Materials.....	180
Stretchable Circuits.....	181
Final Finishes.....	182
<b>Technical Challenges .....</b>	183

**Section 6: Trends and Challenges**

Verbatim Comments from OEMs.....	185
Verbatim Comments from PCB Fabricators .....	189

**Appendices:**

Survey Questionnaires .....	193
Current IPC Market Research Reports.....	213